12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130814001
Add Cu as Alternative Wire Base Metal for Selected Device(s)
Change Notification / Sample Request

Date: 8/26/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130814001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CSD95375Q4M	null
CSD97374Q4M	null
CSD97376Q4M	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130814001	PCN Date:	08/26/2013
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)		
Customer Contact:	PCN Manager	Phone: +1(214)480-6037	Dept: Quality Services
Proposed 1st Ship Date:	11/26/2013	Estimated Sample Availability:	Date provided at sample request

Change Type:					
☐	Assembly Site	☒	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and there will be no other piece part changes.

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

None.

Product Affected: Group 1 devices

DAC34H84IZAY	DAC34H84IZAYR	DAC34SH84IZAY	DAC34SH84IZAYR

Product Affected: Group 2 devices

CSD95375Q4M	CSD97374Q4M	CSD97376Q4M

Group 1 : Qualification Data

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: D6567GN0ZWKR (MSL 3-260C)

Package Construction Details

Assembly Site:	PHI (TIPI)	Mold Compound:	4206745
# Pins-Designator, Family:	385-ZWK, BGA	Mount Compound:	4073505
Solder Ball composition	SnAgCu	Bond Wire:	0.80Mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**Biased Temp Humidity	85C/85%RH (600hrs)	78/0	-	-
**Unbiased HAST	110C/85%RH (264hrs)	78/0	78/0	78/0
**High Temp. Storage Bake	150C (600 hrs)	78/0	78/0	78/0
**T/C -65C/150C	-55C/+125C (1000 Cyc)	78/0	78/0	78/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass

Notes **- Preconditioning sequence: Level 3-260C.

Qual Vehicle 2: DAC34H84IZAY (MSL 3-260C)

Package Construction Details

Assembly Site:	PHI (TIPI)	Mold Compound:	4206745
# Pins-Designator, Family:	196-ZAY, BGA	Mount Compound:	4073505
Solder Ball composition	SnAgCu	Bond Wire:	0.95Mil Au

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**Autoclave	121C, 2atm (96hrs)	77/0	77/0	77/0
** Life Test	125C (1000hrs)	116/0	116/0	116/0
**Unbiased HAST	110C/85%RH (264hrs)	77/0	77/0	77/0
**T/C -65C/150C	-55C/+125C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass

Notes **- Preconditioning sequence: Level 3-260C.

Group 2 : Qualification Data			
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Qual Vehicle 1: CSD97374Q4M (MSL 2-260C)			
Package Construction Details			
Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	8-DPC, VSON	Mount Compound:	4211089
Lead frame (Finish, Base)	NiPdAu, Cu	Bond Wire:	0.96Mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**Autoclave	121C/100% RH (96hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH 80% Rated Vds (96hrs)	77/0	77/0	77/0
**T/C -65C/150C	-55C/+125C (1000 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes **- Preconditioning sequence: Level 2-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com